

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5710165

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIA-MING LIU	07/29/2019
TING-YING SHEN	07/29/2019
MING-CHE LIN	07/29/2019
RECEIVING PARTY DATA	
Name:	WINBOND ELECTRONICS CORP.
Street Address:	NO. 8 KEYA 1ST RD., DAYA DISTRICT, CENTRAL TAIWAN SCIENCE PARK
City:	TAICHUNG CITY
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16558630
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	0941/3685PUS1
NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe McKinney Muncy/
DATE SIGNED:	09/10/2019
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, Chia-Ming LIU, Ting-Ying SHEN and Ming-Che LIN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: RESISTIVE RANDOM ACCESS MEMORY CIRCUIT

Filed: _____ Serial No. _____

Executed on: _____

WHEREAS, Winbond Electronics Corp. of No. 8 Keya 1st Rd., Daya District, Central Taiwan Science Park, Taichung City, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chia-Ming LIU
Chia-Ming LIU

July 29, 2019
Date

Ting-Ying Shen
Ting-Ying SHEN

July 29, 2019
Date

Ming-Che Lin
Ming-Che LIN

July 29, 2019
Date